2SK3064G

Silicon N-channel MOSFET

For switching circuit

For rechargeable buttery pack (Li^+ ion buttery, etc.)

■ Features

- High gate-source voltage (Drain open) V_{GSO}
- Low gate threshold voltage V_{th}

■ Package

- Code
  SMini3-F2
- Marking Symbol: 2D
- Pin Name
  1: Gate
  2: Source
  3: Drain

■ Absolute Maximum Ratings $T_a = 25°C$

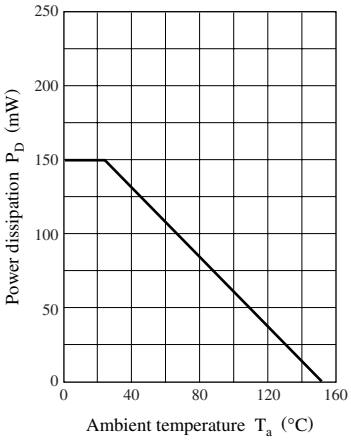
Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V_{DSS}	30	V
Gate-source voltage (Drain open)	V_{GSO}	±20	V
Drain current	I_D	100	mA
Peak drain current	I_{DP}	200	mA
Power dissipation	P_D	150	mW
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

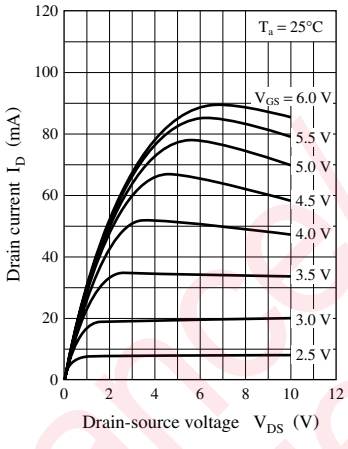
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source cutoff current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0 V			0.1	µA
Gate-source cutoff current	I_{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V			±1.0	µA
Gate threshold voltage	V_{th}	V_{DS} = 5 V, I_D = 1 µA	1.0		2.0	V
Forward transfer admittance	$\|Y_{fs}\|$	V_{DS} = 5 V, I_D = 10 mA	15			mS
ON resistance	R_{on}	V_{GS} = 5 V, I_D = 10 mA		30	50	Ω
Turn-on time	t_{on}	V_{DD} = 5 V, V_{GS} = 0 V to 5 V R_L = 200 Ω		150		ns
Turn-off time	t_{off}	V_{DD} = 5 V, V_{GS} = 5 V to 0 V R_L = 200 Ω		35		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. Observe precautions for handling. Electrostatic sensitive devices.

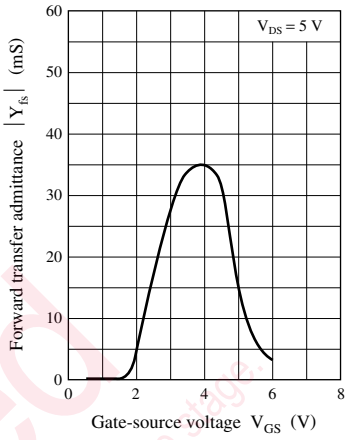
P_D — T_a



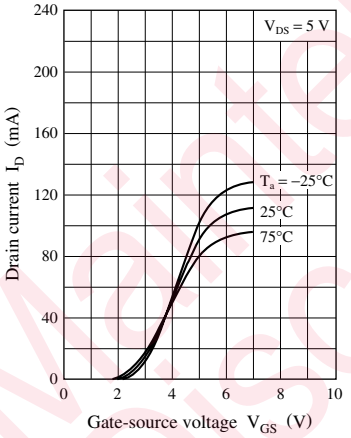
I_D — V_{DS}

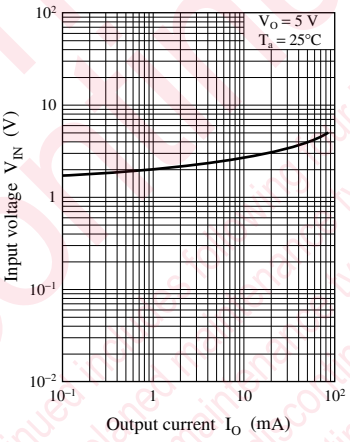


$|Y_{fs}|$ — V_{GS}



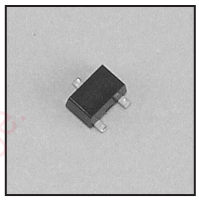
I_D — V_{GS}

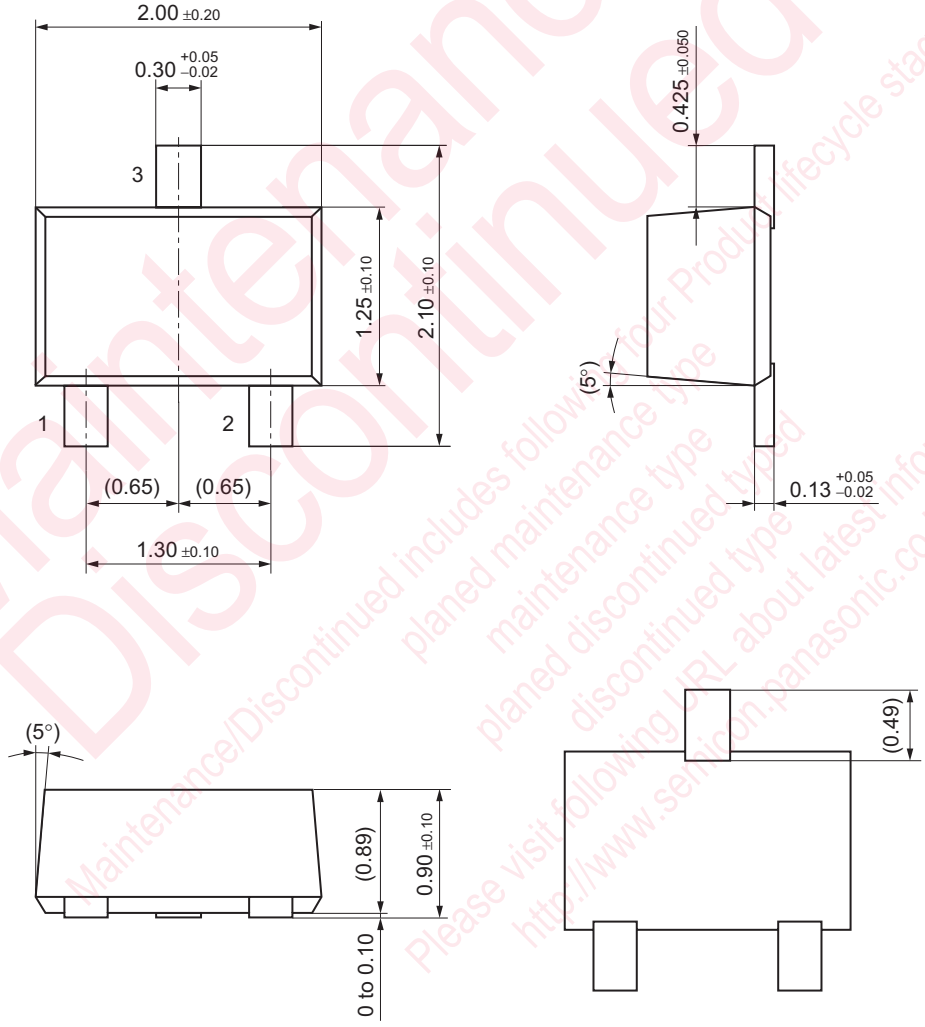




SMini3-F2

Unit: mm





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